Communications & PR Review

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INDIA ELECTRONICS & SEMICONDUCTOR ASSOCIATION
India's ESDM Leadership and Knowledge Partner

COVERAGE HIGHLIGHTS

FINANCIAL EXPRESS
Read to Lead

From design to silicon IP

OWNING INTELLECTUAL PROPERTY IS KEY – BUT THE PATH IS LONG AND COMPLEX

SUDHIR CHOWDHARY

GROWTH DYNAMICS

- India's strong chip design capabilities are not translating into IP ownership, leaving most of the semiconductor value overseas
- IP ownership determines where long-term value and influence sit in the ecosystem
- Manufacturing makes 5-10% of value, design and IP 20-30%, while chip brands command over 50%
- Building a domestic market could help move from services to semiconductor IP creation

ASHOK CHANDAK, PRESIDENT, IESA AND SEMI INDIA: India has good design talent, but much of it is channelled into short-term services revenue

JAYASHANKAR NARAYANANKUTTY, GROUP DIRECTOR, CADENCE DESIGN SYSTEMS: Key gaps include limited deeptech risk capital, few system-level architects & weak academia-industry links

ARJUN MALHOTRA, CO-FOUNDER, HCL AND EPIC FOUNDATION: The domestic market is now large enough to enable the design of India-specific products at scale

FOR DECADES, INDIA has built strong capabilities in engineering services and chip design. Global majors such as Qualcomm and Intel run large R&D centres in Bengaluru, Hyderabad and Noida, with Indian engineers contributing to some of the world's most advanced chips. Yet, the ownership of these designs—the patents, architectures, and licensing rights—largely remains overseas.

GEOPOLITICAL TENSIONS EMERGE AS KEY BUSINESS RISK

India Inc reworks strategy amid global uncertainty

VIVEAT PINTO, RAGHAVENDRA KAMATH, OJASVI GUPTA, NITIN KUMAR & V NARAYANAN
Mumbai/Delhi/Chennai, April 17

MOHIT MALHOTRA, GLOBAL CEO, DABUR: In these dynamic times, assumptions regarding business growth, inflation and currency have to be looked at frequently

SHAILESH CHANDRA, PRESIDENT, SIAM: April will be a litmus test. We have witnessed stress levels in the supply chain in April, as we did in March

ASHOK CHANDAK, PRESIDENT, SEMI INDIA AND IESA: We are seeing 'friend-shoring', export controls, and strategic stockpiling becoming the new normal, especially in semiconductors

GEOPOLITICAL TENSIONS ARE no longer distant flash-points—they are fast becoming balance-sheet risks and pressing boardroom concerns.

FINANCIAL EXPRESS
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Electronics makers to cut output by 10-20% amid memory chip squeeze

GULVEEN AULAKH
New Delhi, 29 April

MEMORY CHIP PRICES HAVE SURGED 4-5 TIMES IN THE PAST FEW QUARTERS, PROMPTING REDUCED PRODUCTION OF ENTRY-LEVEL DEVICES

A shortage in the supply of memory chips used in electronics manufacturing is forcing original equipment manufacturers (OEMs) and electronics manufacturing services (EMS) firms in India to recalibrate production, with some players cutting output by 10-20 per cent for the remainder of the year.

The shortage is affecting the production of smartphones, televisions, servers, set-top boxes and routers, as manufacturers grapple with both rising costs and tightening availability of memory components.

categories are being impacted. Mobile phones will be hit the hardest, followed by personal computers, servers and set-top boxes. Other consumer electronics such as TVs, and even automotive-grade memory availability, are also facing shortages," said Tarun Pathak, research director at Counterpoint Research. "Overall, production

electronics categories, with manufacturing taking an equivalent hit," he added.

Memory chip prices have surged four to five times over the past few quarters, prompting several manufacturers to reduce production of entry-level devices and redirect capacity towards premium products with higher average selling prices (ASP) in an attempt to protect margins.

"Rather than implementing outright production stops, OEMs are responding through a 'survival of the premium' strategy, using configuration adjustments, tighter cost controls and price increases to offset shrinking margins," said Ashok Chandak, president of the Indian Electronics and Semiconductor Association (IESA).

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Business Standard

the political and business daily
www.pbdodisha.in

IESA Hails 3DGS Ground breaking as India's Big Leap in Advanced Semiconductor Packaging

BHUBANESWAR: The India Electronics and Semiconductor Association (IESA) welcomes the inauguration of 3DGS Semicon's advanced packaging facility in Odisha by Union Minister Ashwini Vaishnaw and Minister Mohan Charan Majhi, calling it a strong demonstration of India's shift from intent to execution in semiconductors.

IESA ವತಿಯಿಂದ 2026-27ನೇ ಹಣಕಾಸು ವರ್ಷಕ್ಕೆ ಹೊಸ ಕಾರ್ಯಕಾರಿ ಮಂಡಳಿ ಘೋಷಣೆ: ನವೀನ್ ಬಿಷ್ಣೋಯ್ ಅಧ್ಯಕ್ಷರಾಗಿ ನೇಮಕ

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"Driven by strong artificial intelligence (AI) demand and superior margins, memory manufacturers are increasingly allocating capacity toward high-bandwidth memory (HBM), tightening supply for conventional dynamic random access memory (DRAM) and NAND (memory chips that retain data without power)... We are already seeing this reflect in pricing trends — DRAM prices have firmed up sharply and are expected to remain elevated, while HBM continues to command a significant premium due to constrained supply," Ashok Chandak, President, India Electronics and Semiconductor Association (IESA), told *businessline*.

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"Talent is the new geopolitical currency... supply chain resilience is now moving towards talent chain resilience," said Ashok Chandak, president of the Indian Electronics and Semiconductor Association, capturing the broader shift underway.

The idea that Indian professionals will simply return home en masse is, at best, premature.

"It's easier said than done," said Chandru Iyer, Deputy High Commissioner for Karnataka, pointing to lifestyle expectations, family considerations, and work culture differences that complicate relocation decisions.

FINANCIAL EXPRESS

From design to silicon IP – The complex path of owning intellectual property

OWNING INTELLECTUAL PROPERTY IS KEY–BUT THE PATH IS LONG AND COMPLEX

Written by Sudhir Chowdhary

Updated:April 16, 2026 07:21 IST

Can India reclaim the richest part of the

For decades, India has built formidable strength in engineering services and chip design. Global majors – from Qualcomm to Intel – operate large R&D centres in Bengaluru, Hyderabad, and Noida. Indian engineers contribute to some of the world's most advanced chips. Yet, the ownership of those designs – the patents, architectures, and licensing rights – largely resides outside the country.

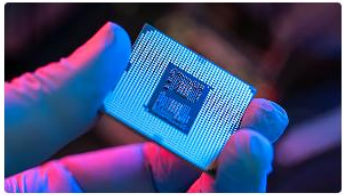
This is the imbalance that IT minister Ashwini Vaishnaw has repeatedly highlighted: India powers innovation, but does not always profit from it. Design services without intellectual property (IP) ownership are akin to leaving the most valuable part of the value chain on the table. In the semiconductor industry, IP ownership ultimately determines where long-term value, strategic leverage, and ecosystem resilience lie.

ALSO READ
Entry-level hiring diversifies as AI roles gain ground

To address this, the government has begun shifting its focus. Its push into semiconductor manufacturing – backed by initiatives such as the Design Linked Incentive (DLI) scheme – is aimed at promoting indigenous IP and moving beyond assembly-led participation. Yet beneath this policy momentum lies a more structural question: can India truly move from participation to ownership in the global semiconductor value chain?

FORTUNE

India advances in chip value chain with 3DGS facility; semiconductor market expected to hit $103 billion by 2030



The inauguration of 3DGS Semicon's advanced packaging facility in Odisha marks a significant step in India's semiconductor journey, with India Electronics and Semiconductor Association (IESA) calling it a clear sign of movement from policy intent to execution.

3DGS Semicon, the India arm of US-based 3D Glass Solutions, known for its glass-based packaging technologies used in high-frequency and high-performance semiconductor applications. The Odisha unit is among the early facilities in India focused on heterogeneous integration – an advanced packaging approach that integrates multiple chips into a single system to improve performance and efficiency.

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The facility, inaugurated in the presence of Union Minister Ashwini Vaishnaw and Odisha Chief Minister Mohan Charan Majhi, will manufacture specialised packaging solutions that sit between chip fabrication and final product assembly – an area where India has had limited domestic capacity.

Advanced packaging emerges as key lever

IESA President Ashok Chandak said the unit represents a meaningful capability addition as advanced packaging, increasingly seen as critical to semiconductor performance and system integration.

He noted such investments can help India move beyond participation to value capture by strengthening supply chains, enabling chiplet-led innovation, and supporting next-generation product integration.

With global players looking beyond traditional node scaling, advanced packaging has become a focal point for enhancing performance and efficiency, making domestic capabilities in this segment particularly relevant.

From design base to manufacturing depth

According to Chandak, the development reflects the growing maturity of India's semiconductor ecosystem, historically anchored in design and engineering.

The addition of packaging and product commercialisation capabilities signals a gradual broadening of the value chain within the country, pointing to progress toward manufacturing more sophisticated semiconductor products.

ET Manufacturing
From The Economic Times

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IESA elects Marvell's Navin Bishnoi as chairperson for FY27

"India stands at an inflection point—moving decisively from semiconductor ambition to large-scale execution. As Chairperson of IESA, my priority is clear: enable time-bound outcomes across the value chain—design, manufacturing, OSAT, and supply chain resilience," Bishnoi said.

ETTelecom Desk • ETTelecom
Published On Apr 20, 2026 at 01:32 PM IST

The India Electronics and Semiconductor Association (IESA) has elected Navin Bishnoi as the chairperson of its new executive council (EC) for FY26-27.

OUTLOOK BUSINESS
THINK BEYOND. STAY AHEAD.

PM Modi Inaugurates India's Second Semiconductor Plant, Kaynes Semicon Begins Operations

Summary of this article

- Prime Minister Modi inaugurated Kaynes Semicon's ₹3,300 crore facility in Sanand, Gujarat
- The plant is India's second operational semiconductor unit under the India Semiconductor Mission
- Initial commercial production focuses on Intelligent Power Modules for EVs and industrial systems

Prime Minister Narendra Modi on Tuesday inaugurated Kaynes Semicon's ₹3,300 crore semiconductor facility at Sanand GIDC in Ahmedabad, according to a report by Business Today.

The move is part of India's push to build domestic chip manufacturing capacity and reduce dependence on imports. The plant, an outsourced semiconductor assembly and test (OSAT) unit, has begun commercial operations and will focus on assembly, packaging, and testing, critical steps in the global semiconductor value chain.

2026.04.13

【IESAチェンダック会長に聞く】インド半導体、「政策」から実行へ 2030年に1000億ドル産業に飛躍

A・チェンダック会長

マイクロンの拡立工場を訪問したモディ首相（中央）

半導体産業の育成に向け、2021年12月に国家プロジェクト「インド半導体ミッション（ISM）」を打ち出したインド。半導体の一大消費地から、世界的な半導体・ディスプレーの製造拠点への転換を進めている。26年からは次の段階「ISM2.0」に入り、装置・材料・設計・サプライチェーンまでを包含するフルスタック型の政策へ移行する。30年には半導体だけで1000億ドル規模を目指す。インド電子・半導体産業協会（IESA）会長／SEMI India代表のアショーク・チャンダク氏に、現状と展望を聞いた。

市場拡大とサプライチェーン参画

――急速にインドの半導体産業が進展しています。

チャンダック会長　確かに進展は速く、外国企業はインドを重要な投資先として捉えている。州政府も中央政府の政策に協力的になってきた。中央政府は次の段階としてスケールアップと実行を掲げており、関心は国内市場だけでなく、世界のサプライチェーンの一員になることへ移っている。

――年初にIESAが示した市場予測では、30年に半導体が電子産業の25%を占めています。

チャンダック会長　25年に610億ドルの市場規模が、30年には1030億ドルに拡大するとみている。需要をけん引してきたのは携帯端末で、23年は全体の49%を占めた。今後も高機能化に伴い需要は続く。ただし成長を持続させるには、製造と設計の両面で長期戦略と財政支援、国際協力、設計支援（DLI）、サプライチェーン拡充、人材育成が不可欠だ。

設計に強み、弱点補完へ新組織

――新部門「IDSPS」を設置した狙いは。

チャンダック会長　長期戦略を担う組織が必要との声を受け、設計・半導体・パッケージング・システムの4分野を統合した。インドは設計に強みがある一方、R&D（研究開発）や製造技術、パッケージングに課題がある。弱点を補い、成長を加速させる役割を担う。